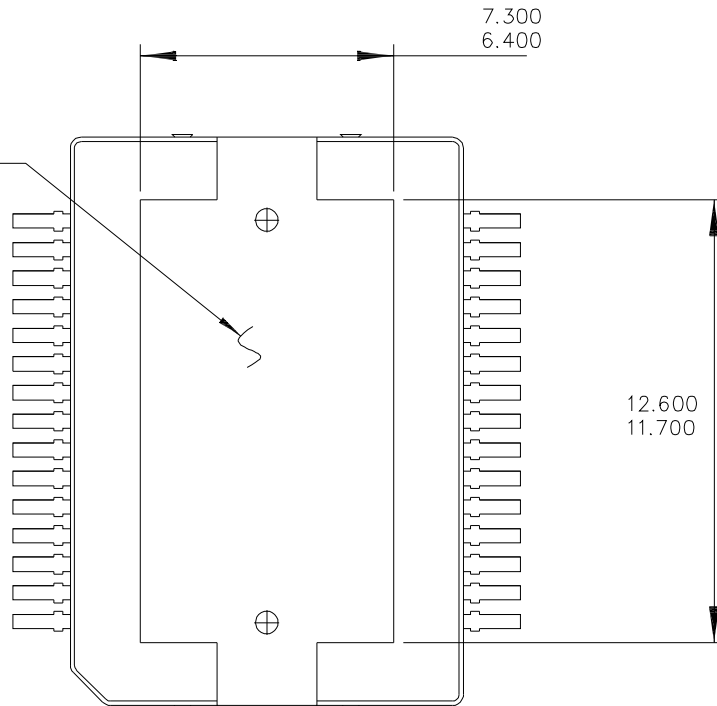


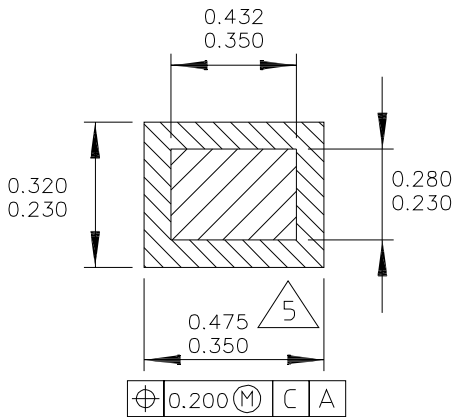
© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 30 LEAD HSOP W/PROTRUDING HEATSINK	DOCUMENT NO: 98ASH70693A	REV: B
	STANDARD: NON-JEDEC	
	SOT1577-1	11 MAR 2016



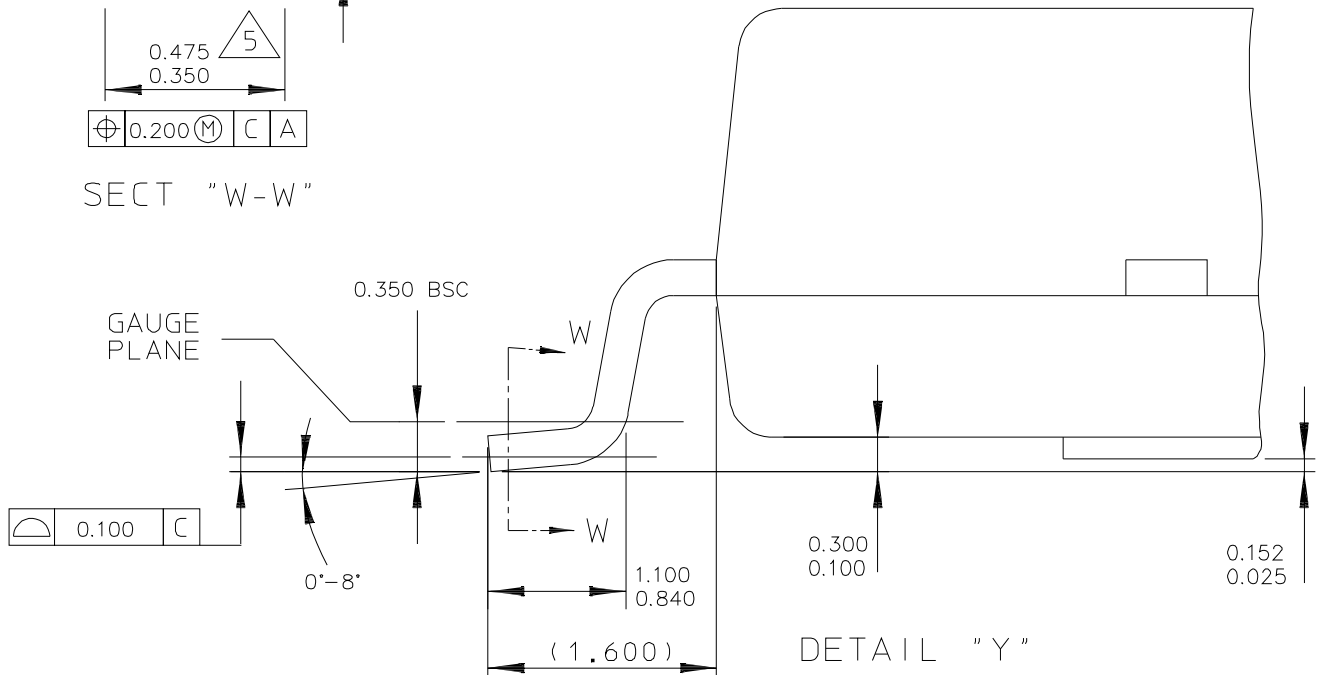
EXPOSED HEATSINK AREA



BOTTOM VIEW



SECT "W-W"



DETAIL "Y"

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 30 LEAD HSOP W/PROTRUDING HEATSINK	DOCUMENT NO: 98ASH70693A	REV: B
	STANDARD: NON-JEDEC	
	SOT1577-1	11 MAR 2016



NOTES:

1. CONTROLLING DIMENSION: MILLIMETER
2. DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DATUM PLANE -H- IS LOCATED AT BOTTOM OF LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
4. DIMENSIONS DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE PROTRUSION IS 0.150 PER SIDE. DIMENSIONS DO INCLUDE MOLD MISMATCH AND ARE DETERMINED AT DATUM PLANE -H-.
5. DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 TOTAL IN EXCESS OF THE DIMENSION AT MAXIMUM MATERIAL CONDITION.
6. DATUMS -A- AND -B- TO BE DETERMINED AT DATUM PLANE -H-.
7. DIMENSIONS DOES NOT INCLUDE TIEBAR PROTRUSIONS. ALLOWABLE TIEBAR PROTRUSIONS ARE 0.150 PER SIDE.

© NXP SEMICONDUCTORS N.V. ALL RIGHTS RESERVED	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 30 LEAD HSOP W/PROTRUDING HEATSINK	DOCUMENT NO: 98ASH70693A	REV: B
	STANDARD: NON-JEDEC	
	SOT1577-1	11 MAR 2016